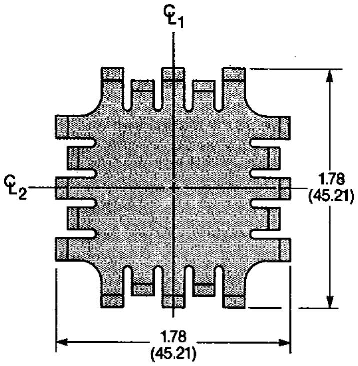
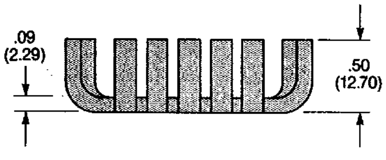

Chipsmall
深圳市津利帝科技有限公司
Geelead Technology Limited
Chipsmall
采购部

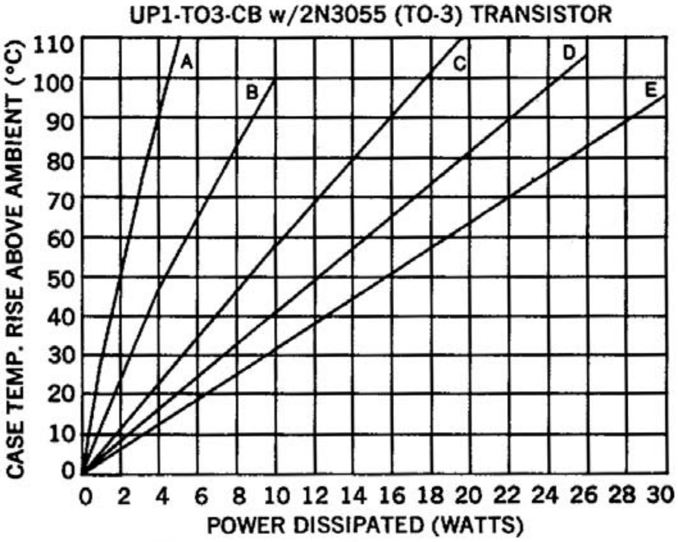
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP1 Series for TO-3 Outline and Stud Mount Devices

Natural Conv. (°C/W): 10.4
Forced Air (°C/W): 3.2
Mounting Envelope: 1.78" x 1.78" x .50"







DESCRIPTION OF CURVES

A. N.C. Horiz. Device Only Mounted to G-10.
B. N.C Horiz. & Vert. With Dissipator.
C. 200 FPM w/Diss.
D. 500 FPM w/Diss.
E. 1000 FPM w/Diss.

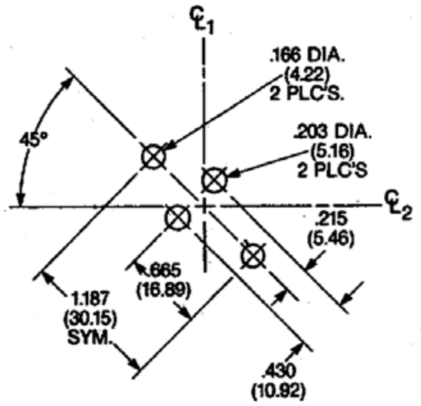
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 0.7 °C/watt for unplated part in natural convection only.
- Derate 0.4 °C/watt for Insulube® part in natural convection only.

Ordering Information

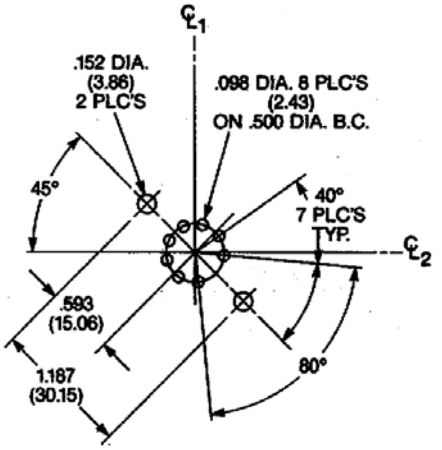
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP1-000-U	UP1-000-CB	UP1-000-B	Undrilled	--	15.5
UP1-T03-U	UP1-T03-CB	UP1-T03-B	T0-3	16	15.5
UP1-T03-46U	UP1-T03-46CB	UP1-T03-46B	T0-3 IC	17	15.5
UP1-436-U	UP1-436-CB	UP1-436-B	TO-3 (4-pin)	18	15.5
UP1-T06-U	UP1-T06-CB	UP1-T06-B	T0-6, T0-36	19	15.5
UP1-T015-U	UP1-T015-CB	UP1-T015-B	T0-15, D0-5	23	15.5
UP-420-U	UP1-420-CB	UP1-420-B	Universal	27	15.5
UP1-T0V-7U	UP1-T0V-7CB	UP1-T0V-7B	Universal	28	15.5

HOLE PATTERNS

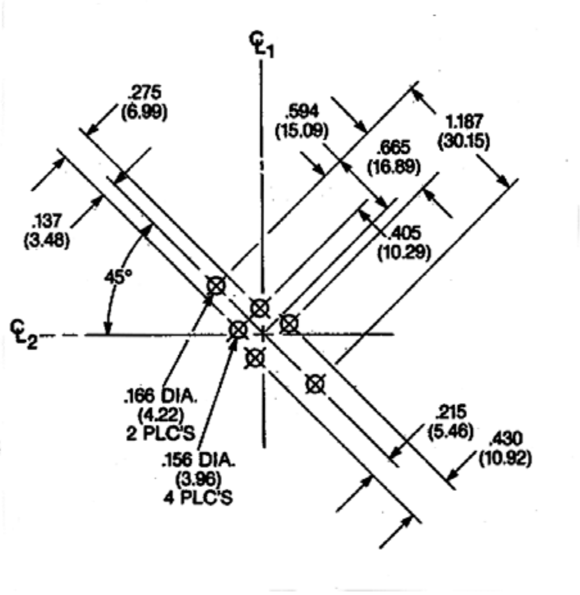
16. Hole pattern no. 1 accommodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



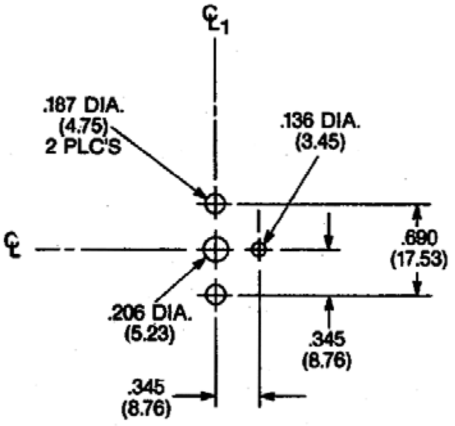
17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



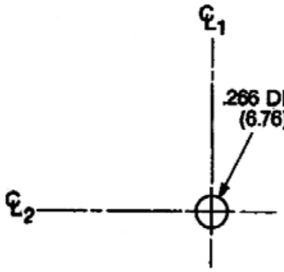
18. Hole pattern no. 436 accommodates t0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



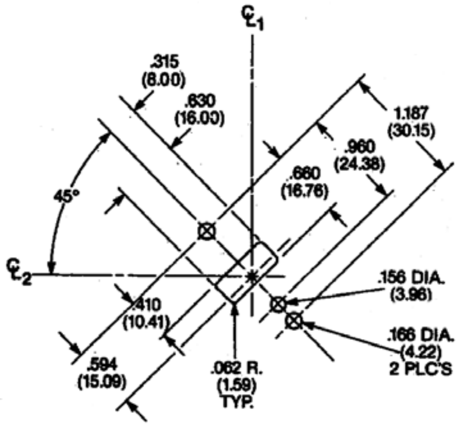
19. Hole pattern no. 2 accommodates T0-6s or T0-36s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



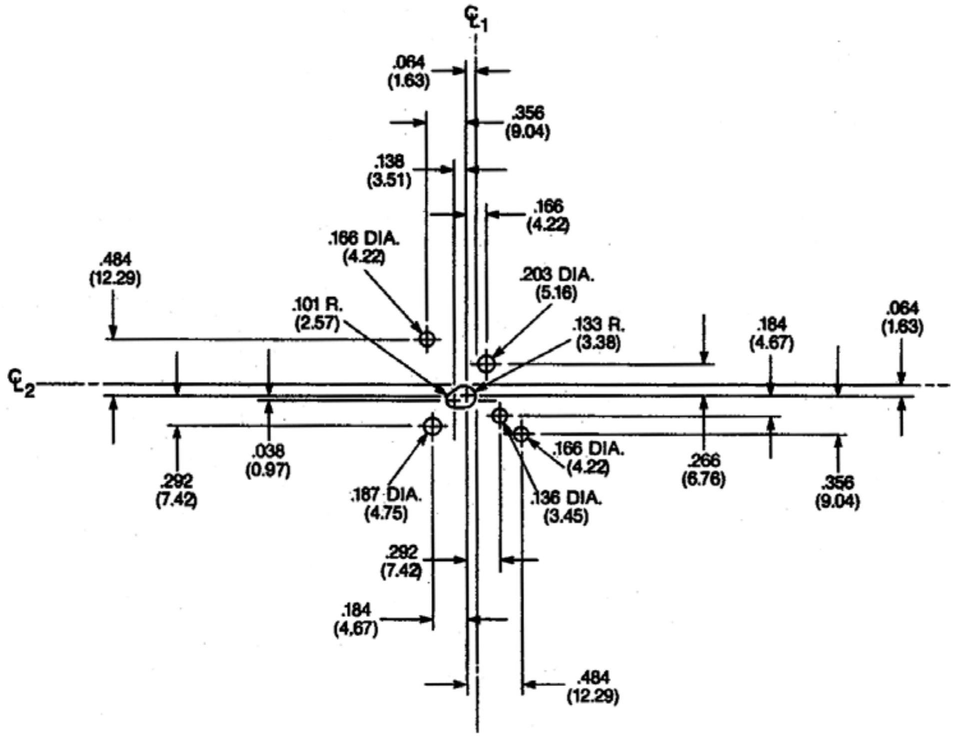
23. Hole pattern no. 3 accommodates T0-15s, D0-5s and other ¼" stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



27. Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



28. Hole pattern no. 64 (Universal) accommodates T0-3s, D0-4s, T0-15s, T0-6s, T0-36s, or other stud mounted devices up to ¼" diameter. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



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